

SPTECH Field Stop Trench IGBTs offer low switching losses, high energy efficiency and high avalanche ruggedness for soft switching applications such as inductive heating, microwave oven, etc.

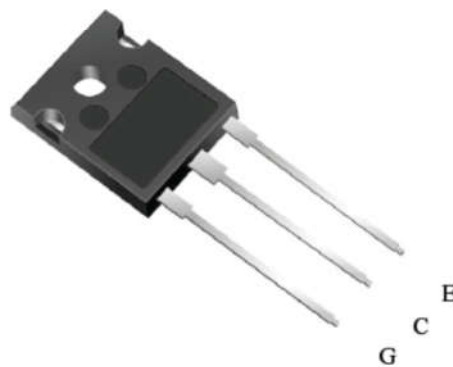
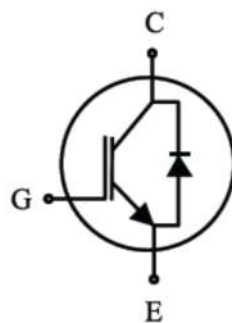
V_{CE}	1200	V
I_C	15	A
$V_{CE(SAT)} \quad I_C=15A$	1.9	V

FEATURES

- Trench-Stop Technology offering :
 - High speed switching
 - High ruggedness, temperature stable
 - Low V_{CEsat}
 - Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Soft current turn-off waveforms
- Enhanced avalanche capability

APPLICATION

- Inductive cooking
- Inverterized microwave ovens
- Resonant converters
- Soft switching applications





Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	V_{CE}	1200	V
DC collector current, limited by T_{jmax} $T_C = 25^{\circ}C$ $T_C = 100^{\circ}C$	I_C	30 15	A
Diode Forward current, limited by T_{jmax} $T_C = 25^{\circ}C$ $T_C = 100^{\circ}C$	I_F	30 15	A
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	45	A
Turn off safe operating area $V_{CE} \leq 1200V$, $T_j \leq 150^{\circ}C$	-	45	A
Operating junction temperature T_j	-	-40...+150	$^{\circ}C$
Storage temperature	T_s	-55...+150	$^{\circ}C$
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s	-	260	$^{\circ}C$

Thermal Resistance

Parameter	Symbol	Max. Value	Unit
IGBT thermal resistance, junction - case	$R_{\theta(j-c)}$	0.7	K/W
Diode thermal resistance, junction - case	$R_{\theta(j-c)}$	1.5	K/W
Thermal resistance, junction - ambient	$R_{\theta(j-a)}$	40	K/W



Electrical Characteristics of the IGBT ($T_j = 25^\circ\text{C}$ unless otherwise specified) :

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Collector-Emitter breakdown voltage	BV_{CES}	$V_{GE}=0V$, $I_C=250\mu A$ ①	1200	-	-	V
Gate threshold voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}$, $I_C=250\mu A$	5.1	5.8	6.4	V
Collector-Emitter Saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V$, $I_C=15A$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	1.9 2.3	2.3 -	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200V$, $V_{GE} = 0V$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	- -	100 1000	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V$, $V_{GE} = 20V$	-	-	100	nA

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic						
Input capacitance	C_{ies}	$V_{CE} = 25V$, $V_{GE} = 0V$, $f = 1MHz$	-	1655	-	pF
Output capacitance	C_{oes}		-	72	-	
Reverse transfer capacitance	C_{res}		-	35	-	
Gate charge	Q_G	$V_{CC} = 600V$, $I_C = 15A$, $V_{GE} = 15V$	-	101	-	nC

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic , at $T_j = 25^\circ\text{C}$						
Turn-off delay time	$td_{(off)}$	$V_{CC} = 600V$, $I_C = 15A$, $V_{GE} = 0/15V$, $R_g=12\Omega$	-	80	-	ns
Fall time	t_f		-	200	-	ns
Turn-off energy	E_{off}		-	0.28	-	mJ

Note:

① BV_{ces} testing without filter could damage the device. BV_{ces} is guaranteed by $I_{ces}@1200V$ test.

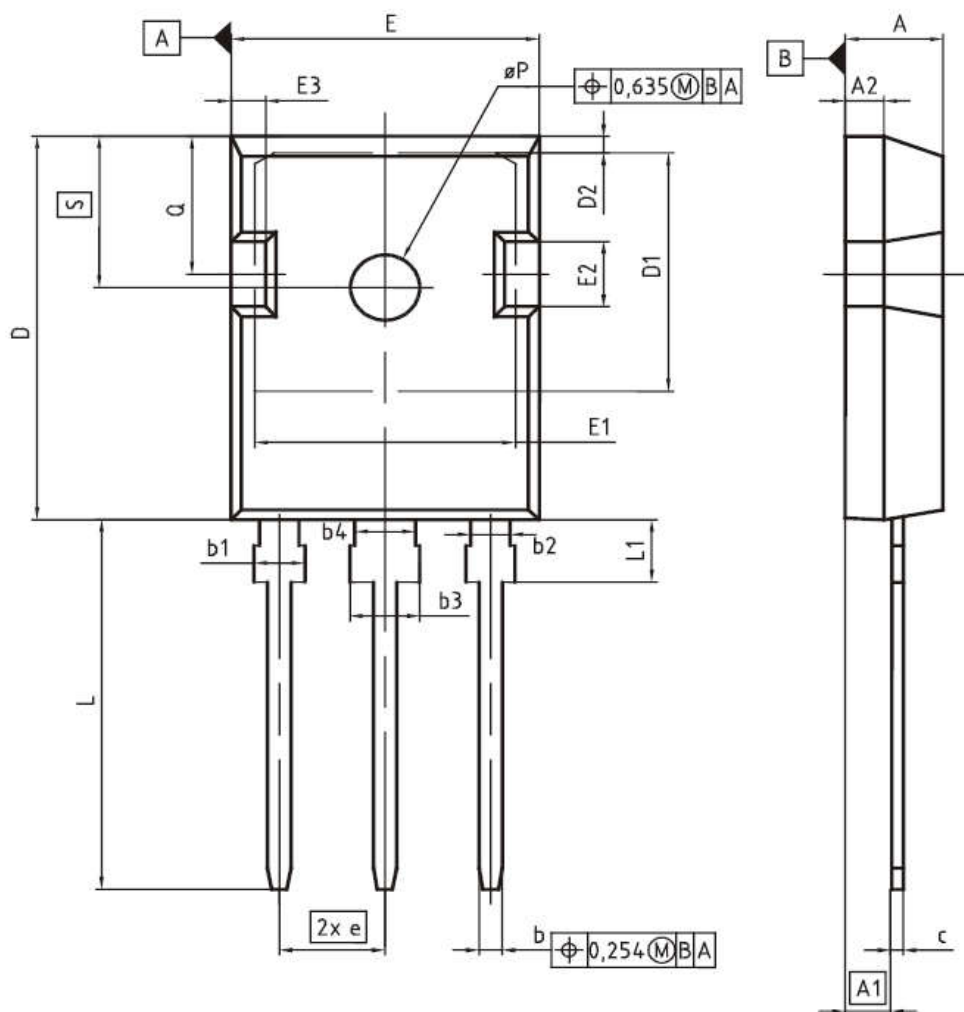


Electrical Characteristics of the DIODE (T_j= 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic						
Diode Forward Voltage	V _{FM}	I _F = 15A	-	2.3	-	V
Reverse Recovery Time	T _{rr}	I _F = 10A, di/dt= 200A/μs	-	70	-	ns
Reverse Recovery Current	I _{rr}		-	5	-	A
Reverse Recovery Charge	Q _{rr}		-	1600	-	nC



PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248